

Title (en)

DEVICE FOR BREAKING SEMICONDUCTOR WAFERS USING A BREAKING BLOCK

Title (de)

VORRICHTUNG ZUM BRECHEN VON HALBLEITERSCHEIBEN MIT HILFE EINES BRECHKEILS

Title (fr)

DISPOSITIF POUR BRISER DES PLAQUETTES À SEMI-CONDUCTEURS AU MOYEN D'UN BLOC DE RUPTURE

Publication

EP 2004375 A1 20081224 (DE)

Application

EP 07723841 A 20070330

Priority

- EP 2007002900 W 20070330
- DE 102006015141 A 20060331

Abstract (en)

[origin: DE102006015141A1] The device has a breaking wedge (3) arranged at a lower side of a semiconductor wafer (1) that is aligned to a preset break line. A counter support is supported at a top side of the semiconductor wafer. The semiconductor wafer is premarked in a starting area of the preset break line, and the breaking wedge is suitably arranged opposite to the plane of the semiconductor wafer such that pressure is exerted at sides of the breaking wedge in the starting area of the preset break line, where the starting area is preprocessed by the marking.

IPC 8 full level

B28D 5/00 (2006.01)

CPC (source: EP)

B28D 5/0011 (2013.01); **B28D 5/0023** (2013.01)

Citation (search report)

See references of WO 2007112984A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC MT NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

DE 102006015141 A1 20071004; EP 2004375 A1 20081224; WO 2007112984 A1 20071011

DOCDB simple family (application)

DE 102006015141 A 20060331; EP 07723841 A 20070330; EP 2007002900 W 20070330